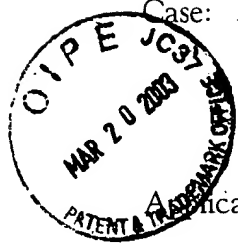


#20/IDS

4-24-03

C. Moore

Case: AMKOR-052A



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Tae Heon Lee et al. )  
Serial No.: 09/687,048 )  
Filed: 10/13/2000 )  
For: Leadframe and semiconductor )  
package with improved solder joint )  
strength )

Art Unit: 2814

Examiner: Nguyen, Dilinh

TECHNOLOGY CENTER 2800

MAR 26 2003

RECEIVED

INFORMATION DISCLOSURE STATEMENT  
PURSUANT TO 37 C.F.R. SECTION 1.97

Assistant Commissioner for Patents  
Washington, D.C. 20231

Dear Sir/Madam:

Pursuant to 37 C.F.R. § 1.97, the following Information Disclosure Statement is submitted as listed on form PTO-1449 enclosed herewith in duplicate. Copies of all disclosure documents are attached hereto for the Examiner's review.

No representation is made that the references disclosed herein legally constitute prior art, or that more relevant references are not available. The disclosure documents enclosed herewith and listed on the attached form (PTO-1449) are printed in the English language and/or accompanied by an Abstract published in the English language.

The references listed herein, when taken alone or in combination are not believed to disclose nor make obvious the invention as claimed in the subject application.

As this Information Disclosure Statement is being submitted after three months from the

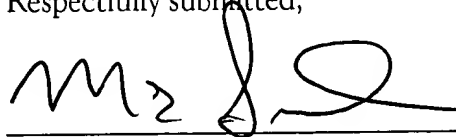
filing date of the subject application and/or after receipt of the initial Office Action, a filing fee in the amount of \$180.00 has been paid by deposit account. The Acknowledgement Receipt, Transmittal, Fee Transmittal, and Electronic Submission of IDS Authorization for this payment are enclosed herein. If any additional fee is required, please charge Deposit Account Number 19-4330.

Dated: 3/17/03

Customer No. 007663

Respectfully submitted,

By:



Mark B. Garred

Registration No.: 34,823

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